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AMENDMENTS TO THE CLAIMS:

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Please cancel claims 2 and 25 without prejudice or disclaimer, and amend the claims as follows:

(Currently Amended) An assembly including at least one microprocessor, comprising:
means for recycling heat, generated by at least one microprocessor, to energy; and
means for directing the heat from said at least one microprocessor to said means for
recycling heat,

wherein said energy is used for cooling said at least one microprocessor.

- 2. (Canceled)
- 3. (Original) The assembly of claim 1, wherein said energy is used to supply an electric power grid.
- 4. (Original) The assembly of claim 1, wherein said means for recycling heat comprises a heat engine.
- 5. (Original) The assembly of claim 4, wherein said heat engine comprises a Stirling heat engine.
- 6. (Original) The assembly of claim 4, wherein said heat engine comprises at least one of an Ericcson heat engine and a thermoacoustic heat engine.
- 7. (Currently Amended) The assembly of claim 1, wherein said means for recycling heat

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comprises a thermoelectric circuit.

- 8. (Original) The assembly of claim 7, wherein said thermoelectric circuit comprises an array of thermocouples.
- 9. (Original) The assembly of claim 1, wherein said means for recycling heat comprises a chemical reaction.
- 10. (Original) The assembly of claim 1, wherein said means for directing the heat comprises at least one of means for conduction, means for convection and means for mass transport.
- 11. (Original) The assembly of claim 1, wherein said means for directing the heat comprises a solid piece of at least one of copper, silicon, aluminum, which is in thermal contact with said at least one microprocessor.
- 12. (Original) The assembly of claim 1, wherein said means for directing heat comprises at least one of a thermal paste, a silver epoxy, a Au-film, a liquid metal, and an oil.
- 13. (Original) The assembly of claim 11, wherein said solid piece comprises a portion of a heat sink, which is used to cool said at least one microprocessor.
- 14. (Original) The assembly of claim 1, wherein said means for directing the heat

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comprises a medium flowing from said at least one microprocessor to said means for recycling heat.

- 15. (Original) The assembly of claim 14, wherein said medium comprises one of a gas and a liquid.
- 16. (Original) The assembly of claim 15, wherein said gas comprises air.
- 17. (Original) The assembly of claim 15, wherein said liquid comprises water.
- 18. (Original) The assembly of claim 1, wherein said means for directing heat comprises a flow channel.
- 19. (Original) The assembly of claim 1, wherein said means for directing heat comprises at least one heat pipe.
- 20. (Original) The assembly of claim 5, wherein said heat engine comprises:
 - a hot reservoir; and
 - a cold reservoir,

wherein the heat from said at least one microprocessor is directed by the means for directing heat via a medium to the hot reservoir of the heat engine.

21. (Original) The assembly of claim 20, further comprising a cooling unit to cool said

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medium.

- 22. (Original) The assembly of claim 21, wherein the cooled medium cools the cold reservoir of the heat engine and said at least one microprocessor.
- 23. (Original) The assembly of claim 21, wherein said cooling unit comprises at least one of a refrigerator, a fan, and a heat exchanger.
- 24. (Currently Amended) A method for use with at least one microprocessor, comprising: directing heat away from said at least one microprocessor; and recycling the heat generated by said at least one microprocessor to energy, wherein said energy is used for cooling said at least one microprocessor.
- 25. (Canceled)
- 26. (Original) The method of claim 24, wherein said energy is used to supply an electric power grid.
- 27. (Currently Amended) An assembly including at least one microprocessor, comprising: a mechanism that recycles heat, generated by at least one microprocessor, to energy; and

a mechanism that directs heat from the at least one microprocessor, to the mechanism that recycles,

wherein said energy is used for cooling said at least one microprocessor.